# PHE845 Series, Class X1, 760 VAC, 105°C



### **Overview**

The PHE845 Series is constructed of metallized polypropylene film encapsulated with self-extinguishing resin in a box of material meeting the requirements of UL 94 V–0.

### **Applications**

For use as a electromagnetic interference (EMI) suppression filter in across-the-line applications requiring X1 safety classification. Suitable for use in situations where failure of the capacitor would not lead to danger of electric shock.

### **Benefits**

Approvals: ENEC, UL, cULClass X1 (IEC 60384-14)

Rated Voltage: 760VAC 50/60Hz
Capacitance range: 0.01 – 1.0 µF
Lead spacing: 22.5 – 37.5 mm

Capacitance tolerance: ±20%, ±10%

Climatic category 40/105/56/B, IEC 60068-1

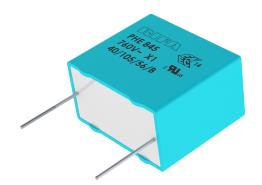
• Tape and reel in accordance with IEC 60286-2

· RoHS Compliant and lead-free terminations

Operating temperature range of -40°C to +105°C

100% screening factory test at 4,250 VDC

Self-healing properties



# **Legacy Part Number System**

PHE845	V	D	5100	M	R06L2
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Capacitance Tolerance	Lead and Packaging Code
X1, Metallized Polypropylene	V = 760	D = 22.5 F = 27.5 R = 37.5	Digits 2-4 indicate the first three digits of the capacitance value. First digit indicates the total number of digits in the capacitance value	K = ±10% M = ±20%	See Ordering Options Table

### **New KEMET Part Number System**

F	845	D	D	103	M	760	С
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Lead and Packaging Code
F = Film	X1, Metallized Polypropylene	D = 22.5 F = 27.5 R = 37.5	See Dimension Table	First two digits indicate the two most significant digits of the capacitance value in picofarads. The third digit is the number of following zeroes.	K = ±10% M = ±20%	760 = 760	See Ordering Options Table



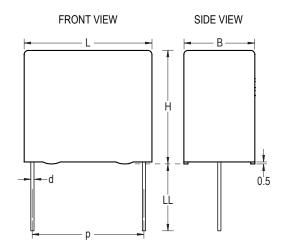
# **Ordering Options Table**

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
	Bulk (Tray)-Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
	Other Lead and Packaging Options			
22.5	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>
	Bulk (Tray)-Long Leads	30 +0/-1	ALW0L	R30L2
	Tape & Reel (Standard Reel)	H <sub>0</sub> = 18.5 +/-0.5	L	R17T0
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 +/-0.5	Р	R17T1
	Standard Lead and Packaging Options			
	Bulk (Tray)-Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
27.5	Other Lead and Packaging Options			
	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>
	Bulk (Tray)-Long Leads	30 +0/-1	ALW0L	R30L2
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 +/-0.5	Р	R17T1
	Standard Lead and Packaging Options			
37.5	Bulk (Tray)-Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
31.3	Other Lead and Packaging Options			
	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>

<sup>(1)</sup> Please specify Bulk (Tray) or Pizza Packaging



# **Dimensions – Millimeters**



KEMET Size	Legacy Size		0	ı	В		Н		L	(	d
Code	Code	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
DD	D13	22.5	+/- 0.4	6.5	Maximum	14.5	Maximum	26.0	Maximum	0.8	+/- 0.05
DG	D17	22.5	+/- 0.4	7.0	Maximum	16.5	Maximum	26.0	Maximum	0.8	+/- 0.05
DM	D15	22.5	+/- 0.4	9.0	Maximum	18.5	Maximum	26.0	Maximum	0.8	+/- 0.05
DR	D18	22.5	+/- 0.4	10.5	Maximum	19.0	Maximum	26.0	Maximum	0.8	+/- 0.05
DT	D16	22.5	+/- 0.4	11.0	Maximum	21.5	Maximum	26.0	Maximum	0.8	+/- 0.05
DW	D20	22.5	+/- 0.4	13.5	Maximum	23.0	Maximum	26.0	Maximum	0.8	+/- 0.05
DY	D19	22.5	+/- 0.4	15.5	Maximum	24.5	Maximum	26.0	Maximum	0.8	+/- 0.05
FE	F11	27.5	+/- 0.4	10.5	Maximum	20.5	Maximum	31.5	Maximum	0.8	+/- 0.05
FG	F12	27.5	+/- 0.4	11.5	Maximum	22.5	Maximum	31.5	Maximum	0.8	+/- 0.05
FK	F03	27.5	+/- 0.4	13.5	Maximum	23.0	Maximum	31.5	Maximum	0.8	+/- 0.05
FS	F15	27.5	+/- 0.4	19.0	Maximum	29.0	Maximum	31.5	Maximum	0.8	+/- 0.05
FV	F16	27.5	+/- 0.4	21.0	Maximum	30.0	Maximum	31.5	Maximum	0.8	+/- 0.05
RH	R04	37.5	+/- 0.5	15.0	Maximum	26.0	Maximum	41.0	Maximum	1.0	+/- 0.05
RK	R02	37.5	+/- 0.5	16.5	Maximum	32.0	Maximum	41.0	Maximum	1.0	+/- 0.05
RM	R03	37.5	+/- 0.5	19.0	Maximum	36.0	Maximum	41.0	Maximum	1.0	+/- 0.05
RP	R06	37.5	+/- 0.5	21.0	Maximum	38.0	Maximum	41.0	Maximum	1.0	+/- 0.05
		No	ta: Saa Ordai	ring Ontions	Table for lea	d length (LL	\ ontions		•		•

Note: See Ordering Options Table for lead length (LL) options.



### **Performance Characteristics**

Dielectric	Polypropylene film					
		anaration undo				
Plates	Metal layer deposited by eva	·				
Winding	Non-inductive type. Triple d	esign.				
Leads	Tinned wire					
Protection	Plastic case, thermosetting	resin filled. Box material is sol	vent resistant and flame retar	dant according to UL94.		
Rated Voltage (V <sub>R</sub> )	760 VAC 50/60 Hz					
Capacitance Range	0.010 μF to 1.0 μF					
Capacitance Values	E6 series (IEC 60063)					
Capacitance Tolerance	±20% standard, ±10% option	on				
Temperature Range	-40°C to 105°C					
Climatic Category	40/105/56/B IEC 60068-1					
Approvals	ENEC, UL, cUL					
Related Documents	EN/IEC 60384-14:2005, UL 60384-14, CAN/CSA E60384-14:09					
	Maximum Values @ +23°C					
	Frequency	C ≤ 0.1 µF	0.1 μF < C ≤ 1 μF			
Dissipation Factor (tanδ)	1 kHz	0.1%	0.1%			
	10 kHz	0.2%	0.4%			
	100 kHz	0.6%	-			
Test Voltage Between Terminals	applicable equipment standar	test is carried out at 4,250 VDC. rds. All electrical characteristics ge the capacitor. KEMET is not	are checked after the test. It is	not permitted to repeat this		
Resonance Frequency	Tabulated self-resonance frequencies f <sub>o</sub> (see Table 1 - Ratings & Part Number Reference)					
	Measured at +25°C ±5°C, according to IEC 60384–2					
Insulation Desistance			according to IEC 60384-2			
Insulation Resistance	C ≤ 0.	Measured at +25°C ±5°C, a	according to IEC 60384-2 etween Terminals	33 µF		
Insulation Resistance		Measured at +25°C ±5°C, Minimum Values B	according to IEC 60384-2 etween Terminals	•		



### **Environmental Test Data**

Test	IEC Publication	Procedure
Endurance	IEC 60384-14:2005	1.25 x V <sub>R</sub> VAC 50 Hz, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10 – 55 Hz at 0.75 mm or 98 m/s <sup>2</sup> No visible damage. No open or short circuit.
Bump	IEC 60068-2-29 Test Eb	1,000 bumps at 390 m/s <sup>2</sup> No visible damage. No open or short circuit.
Change of Temperature	IEC 60068-2-14 Test Na	Upper and lower rated temperature 5 cycles No visible damage.
Active Flammability	IEC 60384-14:2005	V <sub>R</sub> + 20 surge pulses at 4 kV (pulse every 5 seconds)
Passive Flammability	IEC 60384-14:2005	IEC 60384-1, IEC 60695-11-5 Needle Flame Test
Damp Heat Steady State	IEC 60068-2-78 Test Cab	+40°C and 90 – 95% RH, 56 days

# **Approvals**

Certification Body	Mark	Specification	File Number
Intertek Semko AB		EN/IEC 60384-14	SE/0140-17D
UL	c <b>Al</b> us	UL 60384 and CAN/CSA E60384-14:09 (760 VAC)	E73869

# **Environmental Compliance**

All KEMET EMI capacitors are RoHS Compliant.





# **Table 1 – Ratings & Part Number Reference**

Capacitance	Size Code	Max Dir	mensions	in mm	Lead	f <sub>o</sub>	dV/dt	New KEMET	Legacy Part
Value (µF)	(New/Legacy)	В	Н	L	Spacing (p)	(MHz)	(V/µs)	Part Number	Number
0.010	DD/D13	6.5	14.5	26.0	22.5	11	100	F845DD103(1)760(2)	PHE845VD5100(1)(2)
0.015	DD/D13	6.5	14.5	26.0	22.5	9.2	100	F845DD153(1)760(2)	PHE845VD5150(1)(2)
0.022	DD/D13	6.5	14.5	26.0	22.5	7.6	100	F845DD223(1)760(2)	PHE845VD5220(1)(2)
0.033	DF/D17	7.0	16.5	26.0	22.5	6.4	100	F845DF333(1)760(2)	PHE845VD5330(1)(2)
0.047	DM/D15	9.0	18.5	26.0	22.5	5.3	100	F845DM473(1)760(2)	PHE845VD5470(1)(2)
0.068	DR/D18	10.5	19.0	26.0	22.5	4.4	100	F845DR683(1)760(2)	PHE845VD5680(1)(2)
0.10	DT/D16	11.0	21.5	26.0	22.5	3.5	100	F845DT104(1)760(2)	PHE845VD6100(1)(2)
0.15	DW/D20	13.5	23.0	26.0	22.5	3.1	100	F845DW154(1)760(2)	PHE845VD6150(1)(2)
0.22	DY/D19	15.5	24.5	26.0	22.5	2.7	100	F845DY224M760(2)	PHE845VY6220M(2)
0.10	FE/F11	10.5	20.5	31.5	27.5	3.4	100	F845FE104(1)760(2)	PHE845VF6100(1)(2)
0.15	FG/F12	11.5	22.5	31.5	27.5	3.0	100	F845FG154(1)760(2)	PHE845VF6150(1)(2)
0.22	FK/F03	13.5	23.0	31.5	27.5	2.4	100	F845FK224(1)760(2)	PHE845VF6220(1)(2)
0.33	FS/F15	19.0	29.0	31.5	27.5	2.0	100	F845FS334(1)760(2)	PHE845VF6330(1)(2)
0.47	FV/F16	21.0	30.0	31.5	27.5	1.6	100	F845FV474M760(2)	PHE845VZ6470M(2)
0.47	RH/R04	15.0	26.0	41.0	37.5	1.6	100	F845RH474M760(2)	PHE845VW6470M(2)
0.47	RK/R02	16.5	32.0	41.0	37.5	1.6	100	F845RK474(1)760(2)	PHE845VR6470(1)(2)
0.68	RM/R03	19.0	36.0	41.0	37.5	1.2	100	F845RM684(1)760(2)	PHE845VR6680(1)(2)
1.0	RP/R06	21.0	38.0	41.0	37.5	1.0	100	F845RP105M760(2)	PHE845VW7100M(2)
Capacitance Value (µF)	Size Code (New/ Legacy)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	f <sub>o</sub> (MHz)	dV/dt (V/µs)	New KEMET Part Number	Legacy Part Number

<sup>(1)</sup>  $M = \pm 20\%$ ,  $K = \pm 10\%$ .

<sup>(2)</sup> Insert ordering code for lead type and packaging. See Ordering Options Table for available options.



### **Soldering Process**

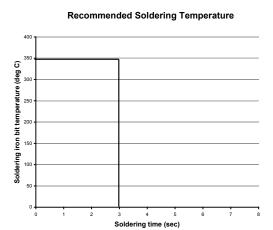
The implementation of the RoHS directive has resulted in the selection of SnAgCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from that of 183°C for SnPb eutectic alloy to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 mm to 15 mm), and great care has to be taken during soldering. The recommended solder profiles from KEMET should be used. Please consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. Please see Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above the recommended limits may result to degradation or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after the curing of surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Please allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

### Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum) with the soldering duration not to exceed more than 3 seconds.

### **Wave Soldering Recommendations**

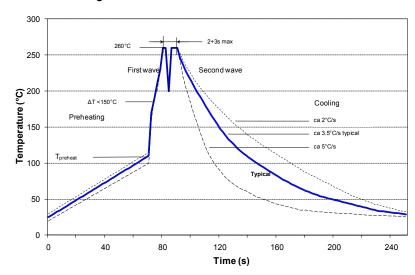


Figure 1

Dielectric		imum Pre emperatu	Maximum Peak Soldering Temperature		
Film Material	Capacitor Pitch ≤ 10 mm	Capacitor Pitch = 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm
Polyester	130°C	130°C	130°C	270°C	270°C
Polypropylene	100°C	110°C	130°C	260°C	270°C
Polyphenylene Sulphide	150°C	150°C	160°C	270°C	270°C



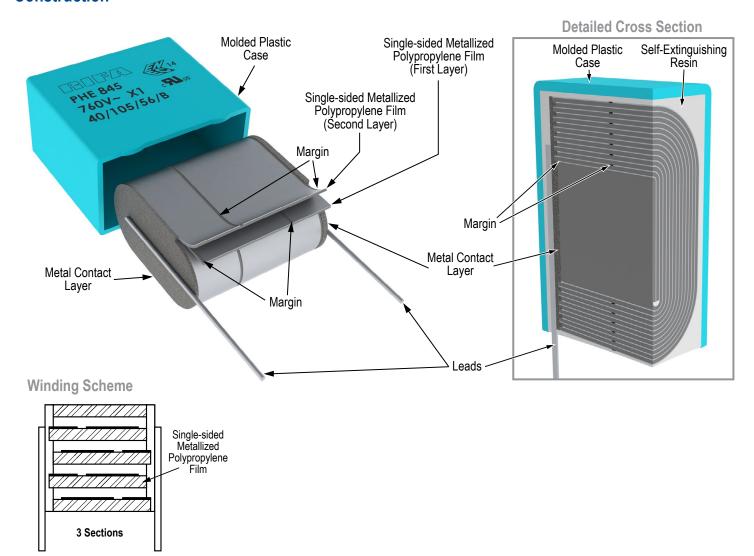
### **Soldering Process cont'd**

#### **Selective Soldering Recommendations**

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as in normal flow soldering without touching the solder. When the board is over the bath, it is stopped and pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document, **however**, **instead of two baths**, **there is only one bath with a time from 3 to 10 seconds**. In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts are not overheated.

### Construction

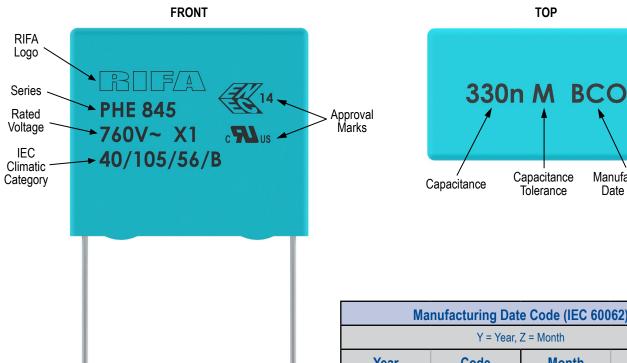




Manufacturing

Date Code

# Marking



Manufacturing Date Code (IEC 60062)									
Y = Year, Z = Month									
Year	r Code Month Code								
2000	M	January	1						
2001	N	February	2						
2002	Р	March	3						
2003	R	April	4						
2004	S	May	5						
2005	T	June	6						
2006	U	July	7						
2007	V	August	8						
2008	W	September	9						
2009	X	October	0						
2010	Α	November	N						
2011	В	December	D						
2012	С								
2013	D								
2014	Е								
2015	F								
2016	Н								
2017	J								
2018	K								
2019	L								
2020	M								



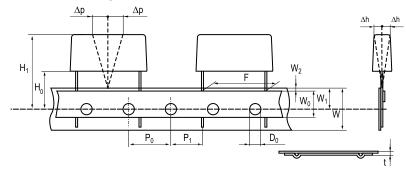
# **Packaging Quantities**

KEMET Size Code	Legacy Size Code	Lead Spacing	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Standard Reel ø 360 mm	Large Reel ø 500 mm	Ammo Bulk (Pizza)
DD	D13		6.5	14.5	26.0	234	300	600	440
DH	D14		8.0	16.0	26.0	186	250	500	352
DM	D15		9.0	18.5	26.0	308	250	500	308
DT	D16	00.5	11.0	21.5	26.0	253	200	400	253
DF	D17	22.5	7.0	16.5	26.0	216	300	600	396
DR	D18		10.5	19.0	26.0	264	200	400	264
DY	D19		15.5	24.5	26.0	176	110	250	176
DW	D20		13.5	23.0	26.0	209	160	300	209
FK	F03		13.5	23.0	31.5	171		250	171
FE	F11		10.5	20.5	31.5	216		350	216
FG	F12		11.5	22.5	31.5	198		300	198
FM	F13		14.5	24.5	31.5	153		250	153
FR	F14		17.5	28.0	31.5	126			126
FS	F15	27.5	19.0	29.0	31.5	117			117
FV	F16		21.0	30.0	31.5	108			108
FH	F17		21.0	12.5	31.5	108			108
FT	F18		31.0	18.5	31.5	72			72
FQ	F19		27.5	16.0	31.5	81			81
RK	R02		16.5	32.0	41.0	105			105
RM	R03		19.0	36.0	41.0	91			91
RH	R04		15.0	26.0	41.0	119			119
RF	R05	37.5	13.0	24.0	41.0	140			140
RP	R06		21.0	38.0	41.0	84			84
RS	R08		28.0	43.0	41.0	54			54



# Lead Taping & Packaging (IEC 60286–2)

### **Lead Spacing 22.5 – 27.5 mm**



# **Taping Specification**

			Dimensions (mm	1)
Description	Symbol	Lead	Tolerance	
		22.5	27.5	Tolerance
Lead spacing	F	22.5	27.5	+0.6/-0.1
Carrier tape width	W	18	18	+1/-0.5
Hold down tape width	W <sub>o</sub>	10	10	Minimum
Hole position	W <sub>1</sub>	9	9	+ 0.75/-0.5
Hold down tape position	W <sub>2</sub>	3	3	Maximum
Feed hole diameter	D <sub>0</sub>	4	4	± 0.2
Feed hole lead space*	P <sub>0</sub>	12.7	12.7	± 0.2**
Centering of the lead wire	P <sub>1</sub>	7.8	5.3	± 0.7
Component alignment	Δh	2	2	± 2
Deviation tape – plane	Δρ	1.3	1.3	Maximum
Tape thickness	t	0.9	0.9	Maximum
Height of component from tape center	H <sub>0</sub> ***	18.5	18.5	± 0.5

<sup>\*</sup>Available also 15mm.

<sup>\*\*</sup>Maximum 1 mm on 20 lead spaces.

<sup>\*\*\*</sup> H<sub>0</sub> = 16.5 mm is available upon request.



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Although all product—related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicted or that other measures may not be required.